ESD5LE5.0C

SOD-523 ESD 静电保护二极管

■Features 特点

Bi-directional 双向 ESD Protection 静电保护

Low capacitance 低电容

■Applications 应用

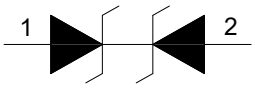
USB 2.0 and USB 3.0 USB 接口

Ethernet 10/100/1000 Base T 以太网

High-speed data lines 高速数据传输总线

Computers and Peripherals 计算机及外部设备

Smart phones & Wireless Systems 智能手机与无线系统



■Device Marking 产品打标 L5

■Absolute Maximum Ratings 最大额定值

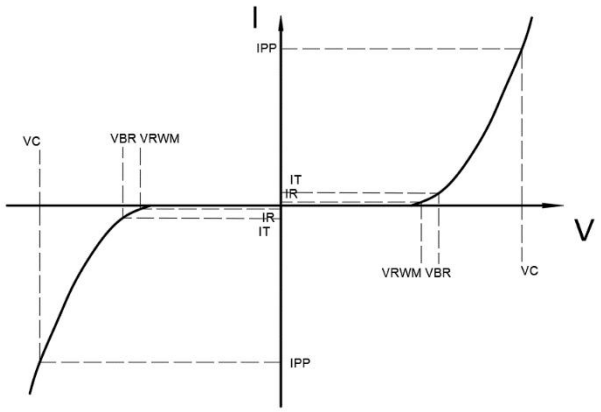
Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
ESD (IEC61000-4-2 contact discharge) @25℃接触放电	V_{ESD}	±30	KV
ESD (IEC61000-4-2 air discharge) @25℃空气放电	V_{ESD}	±30	KV
Peak Pulse Power @25℃峰值脉冲功率	P_{PK}	55	W
Peak Pulse Current @25℃峰值脉冲电流	I_{PP}	5.5	A
Lead Temperature 管脚温度	T_L	260	℃
Lead Solder Time 管脚焊接时间	T_L	10	S
Operating Temperature 工作温度	T_{op}	-40~125	℃
Junction Temperature 结温	T_J	-55~150	℃
Storage Temperature 储存温度	T_{stg}	-55~150	℃

■Electrical Characteristics 电特性

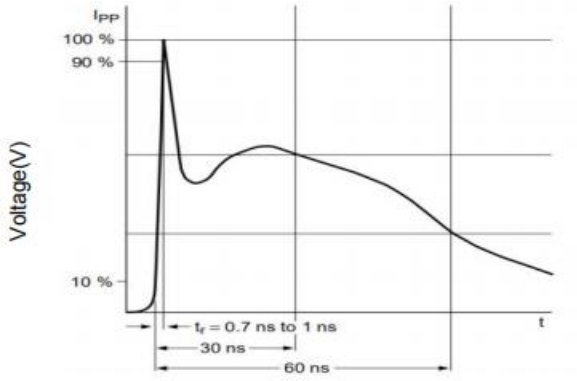
(T_A=25℃ unless otherwise noted 如无特殊说明，温度为 25℃)

Characteristic Parameters 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位	Condition 条件
Reverse Stand-off Voltage 反向工作电压	V_{RWM}			5	V	
Reverse Breakdown Voltage 反向击穿电压	V_{BR}	6.5		8.5	V	I_T=1mA
Reverse Leakage Current 反向漏电流	I_R			0.1	μA	V_{RWM}=5V
Clamping Voltage 钳位电压	V_C		5	7	V	I_{PP}=1A,tp=8/20μs
Clamping Voltage 钳位电压	V_C		8.5	10	V	I_{PP}=5.5A,tp=8/20μs
Junction Capacitance 结电容	C_J		0.3 0.3	0.4 0.4	pF	V_R=0V,f=1MHz V_R=5V,f=1MHz

V_{RWM}	Reverse Working Voltage 反向工作电压
$V_{R(BR)}$	Reverse Breakdown Voltage 反向击穿电压@I_T=1mA
I_T	Test Current 测试电流
I_R	Reverse Leakage Current 反向漏电流@V_{RWM}
V_C	Clamping Voltage 钳位电压
I_{PP}	Reverse Peak Pulse Current 浪涌电流
C_J	Junction Capacitance 结电容 V_{IO}=0V, V_{P-P} = 30mV, f = 1MHz

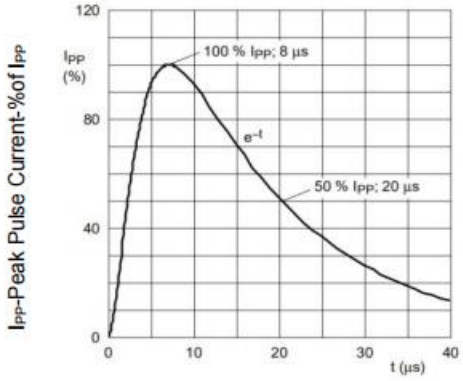


■Typical Characteristic Curve 典型特性曲线



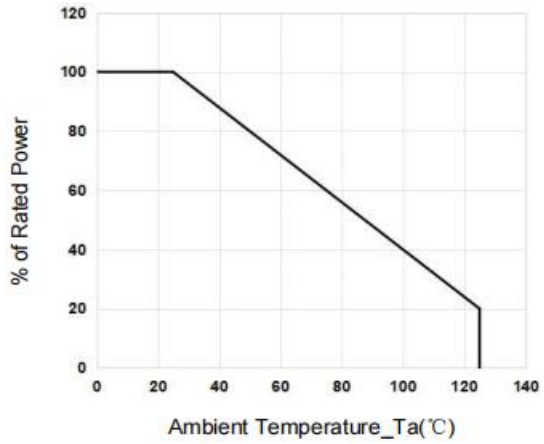
Time(nS)

IEC61000-4-2 Pulse Waveform

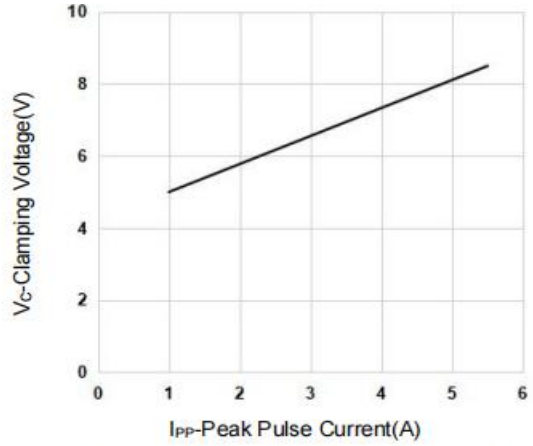


T-Time(µS)

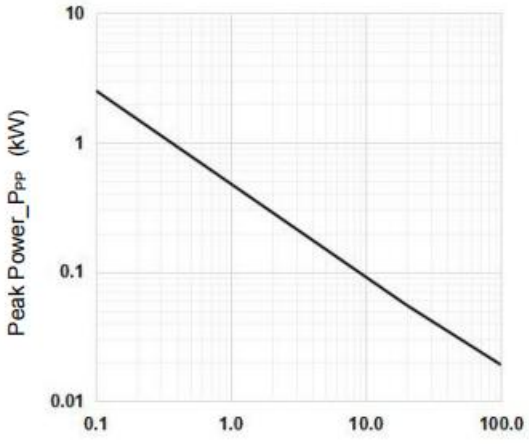
IEC61000-4-5 8X20µs Pulse Waveform



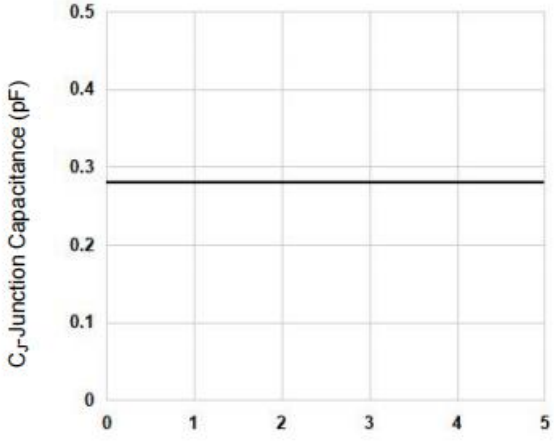
Power Derating Curve



Clamping Voltage vs. Peak Pulse Current



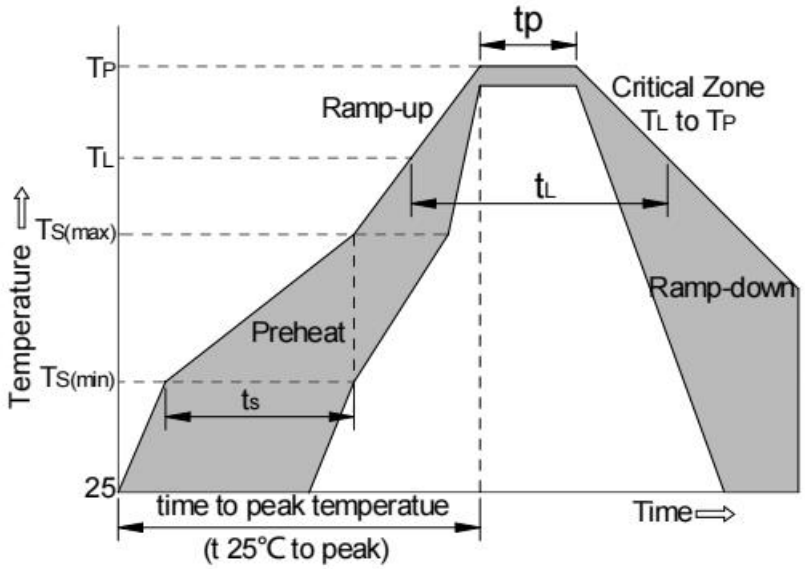
Peak Pulse Power vs. Pulse Time



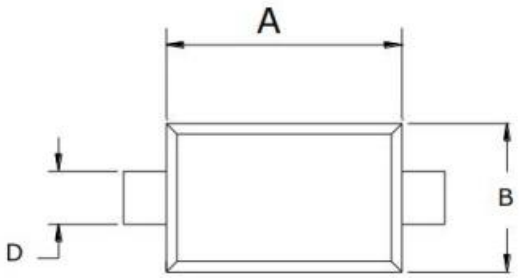
Junction Capacitance vs. Reverse Voltage

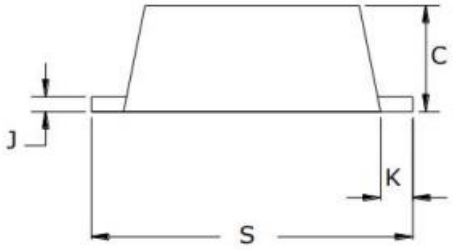
■Soldering Parameters 焊接参数

Reflow Condition		Pb-Free Assembly
Pre-heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
xTime 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



■**Dimension 外形封装尺寸**





SYMBOL	MILLIMETERS	
	MIN	MAX
A	1.10	1.30
B	0.70	0.90
C	0.50	0.70
D	0.25	0.35
J	0.07	0.20
K	0.15	0.25
S	1.50	1.70